



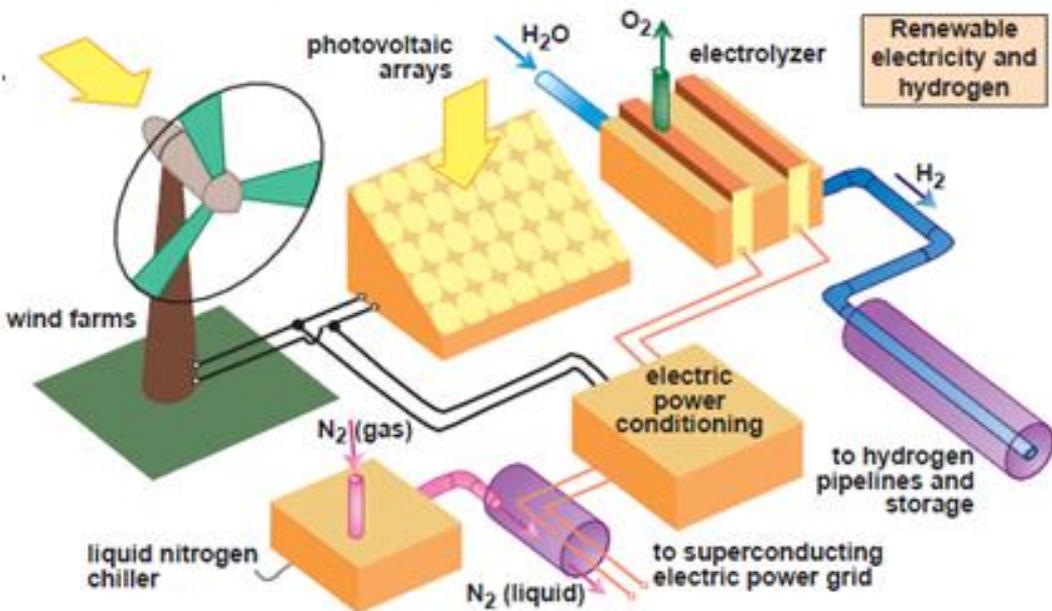
Designing an η -Cu₆Sn₅ alloy anode for sodium ion batteries

ENMA490

5/10/2013

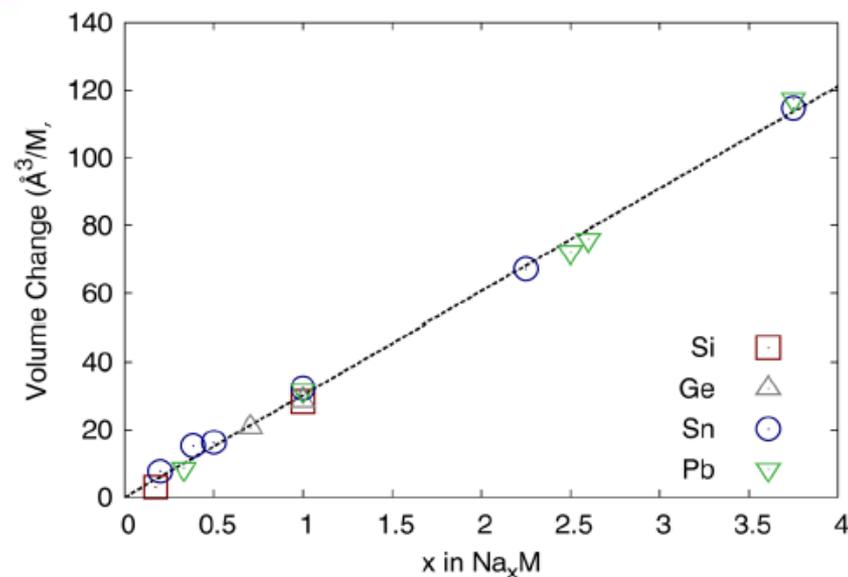
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Motivation

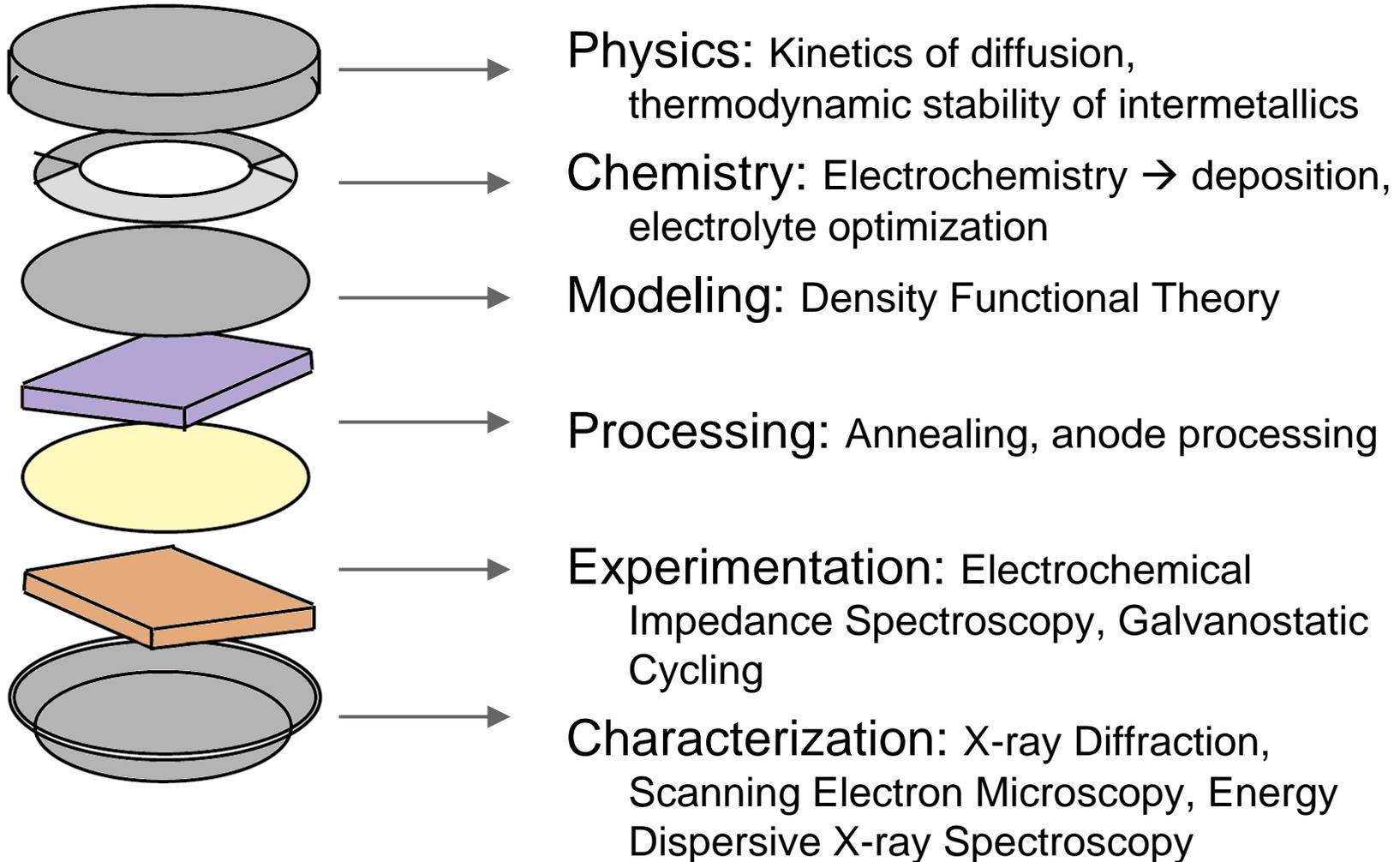


- High capacity anodes for sodium ion batteries have short lifetimes
- Introduce an inert alloying element to reduce expansion

- Grid storage <\$100/kWh is needed to make renewables feasible



Materials Science Aspects: Sandwich Making



Technical Approach

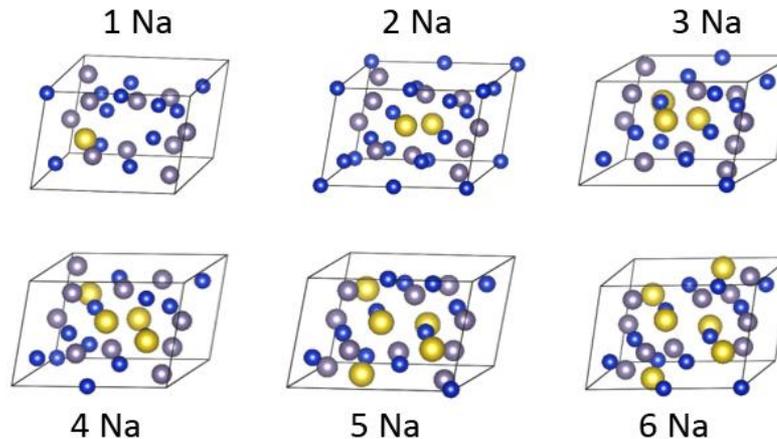
Technical Approach: DFT

Goals

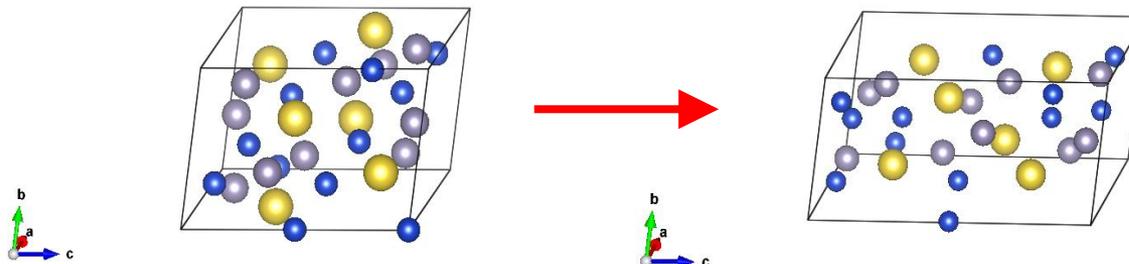
1. **Determine the voltage associated with sodiation.**

- Positive Voltage favors insertion of Na atoms $\rightarrow V = - \left[\frac{\Delta G}{(x_2 - x_1) \cdot F} \right]$

2. **Determine the number of Na atoms that can be inserted in the $\text{Cu}_{12}\text{Sn}_{10}$ unit cell.**

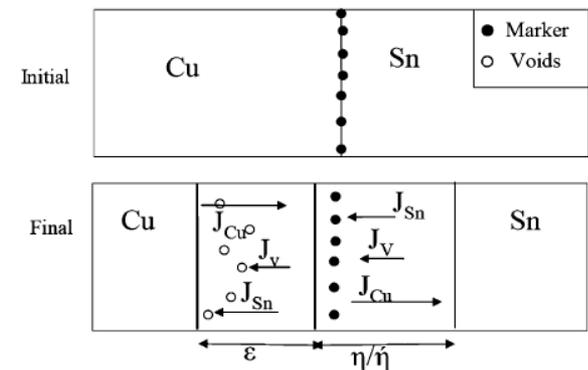
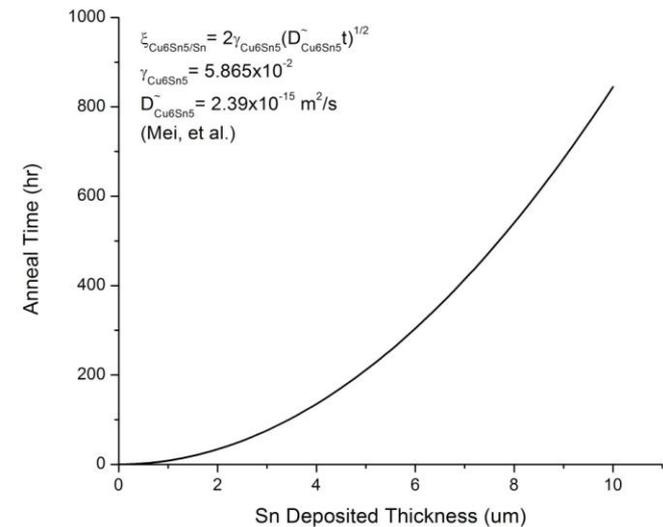


3. **Relax the sodiated structures and determine the volume expansion.**



Technical Approach: IMC Growth

- Cu_6Sn_5 and Cu_3Sn layers will follow a parabolic growth law
 - Cu_6Sn_5 faster overall rate
- $\text{Cu}_6\text{Sn}_5/\text{Sn}$ interface moves with square root of time
- Calculate annealing time necessary for interface to move completely through Sn
- Assume Cu_6Sn_5 and Cu_3Sn begin growing immediately at Cu-Sn interface



Technical Approach: Prototyping

- Electrodeposition
 - Deposit Sn on Cu substrate (cathode), Pt anode
 - Faraday's Law of Electrolysis gives deposition time: $t = (N \cdot n \cdot F) / I$ [N= moles dep., n= charges exch., F= Faraday constant, I= current]
 - Electrodeposition Bath:
 - 0.014M Sn(II) Sulfate, 1.93M methanesulfonic acid, 0.05M hydroquinone
 - Methanesulfonic acid provides benefits over conventional acids (sulfuric, etc)
 - Higher solubility of metal salt (tin sulfate)
 - Helps stabilize Sn(II) ions against oxidation
 - Good electrical conductivity
 - Low toxicity, readily biodegradable
 - Hydroquinone greatly reduces the oxidation of the tin ions in the solution
 - Oxidation of Sn(II) to Sn(IV) results in formation of insoluble tin salts (sludging), removing tin from solution and reducing its ability to deposit

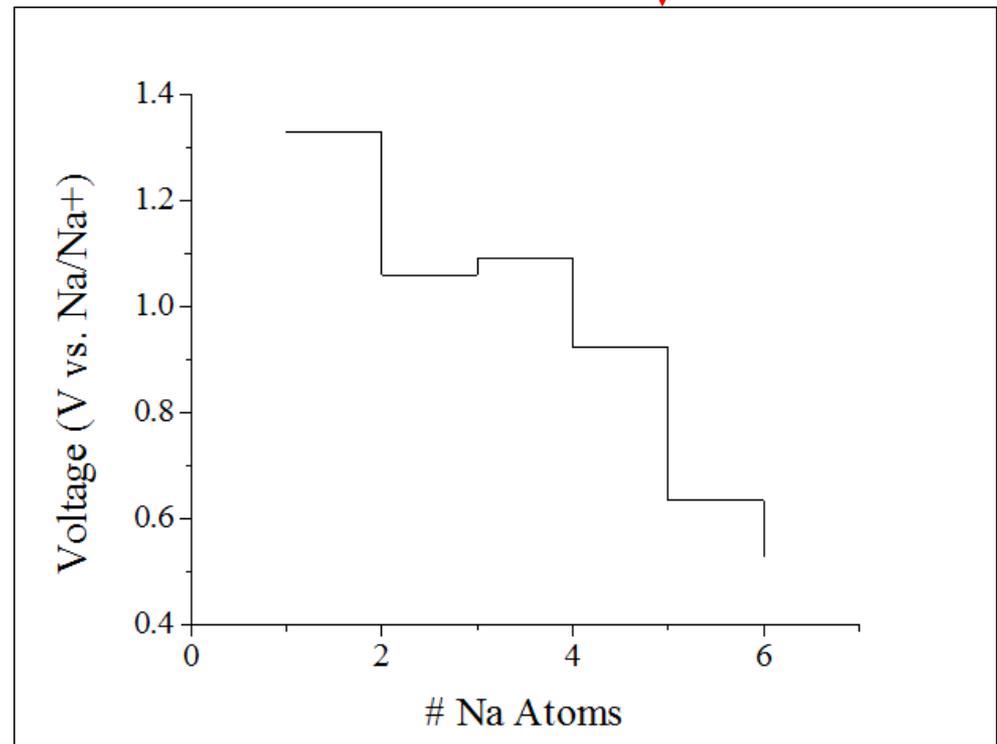
Results

DFT Modeling

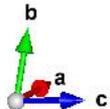
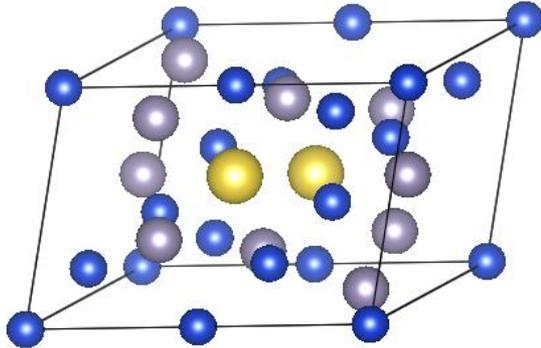
$$\bullet V_{\text{theory}} = - \frac{(E_{\text{defect}} + xE_{\text{Na}} - E_{\text{perfect}})}{x} =$$

-1.306 eV - 83.48 eV

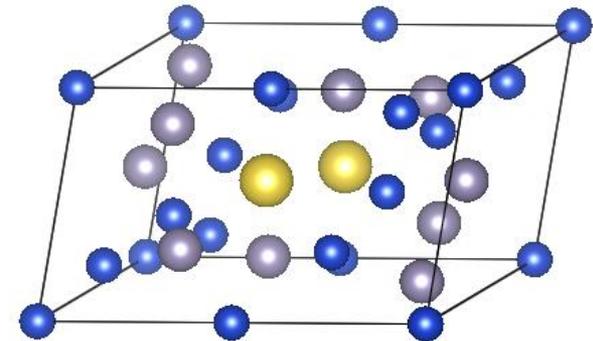
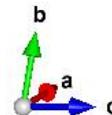
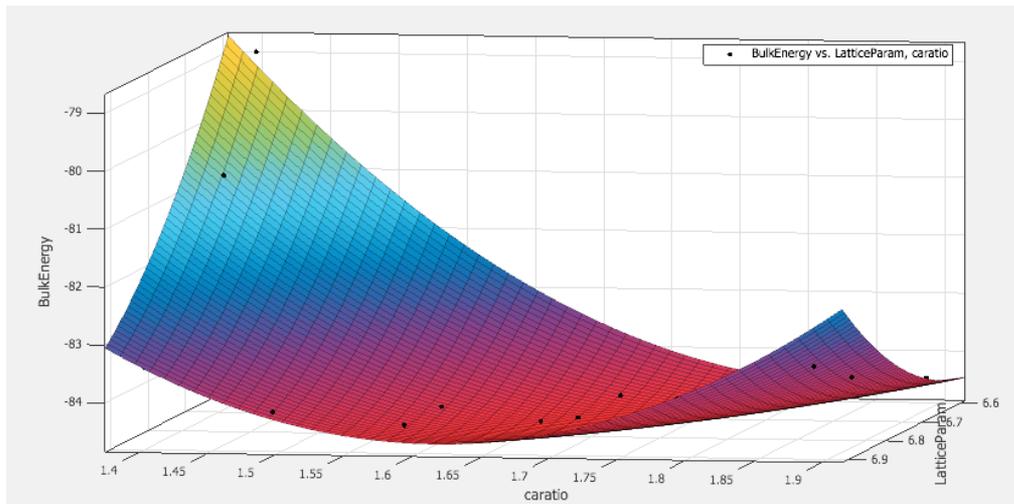
Na-CuSn structure Bulk E (eV)	# Na Atoms
-83.51	1
-82.98	2
-82.82	3
-81.95	4
-80.12	5
-78.81	6



DFT Modeling



- NaSn5 is first to form in pure Sn anodes
- Na₂-Cu₁₂Sn₁₀ Volume = 405.95 Angstroms³
- Relaxed Na₂-Cu₁₂Sn₁₀ Volume = 483.11 Angstroms³
- 19.01% Volume Expansion via DFT
- 30.14% Volume Expansion from Sn-->NaSn5 from reported theoretical values



Electrodeposition

Sample	Cu mass (g) (est.)	Desired Sn mass (g)	Deposition current (mA)	Deposition time (min)	Deposited Sn mass (g)
1	0.0091	0.0141	5.0	90	0.0134
3	0.0091	0.0141	5.0	66	0.0077
5	0.0093	0.0144	5.0	90	0.0117
6	0.0092	0.0143	5.0	90	0.0061
7	0.0076	0.0007	0.5	40	0.0001

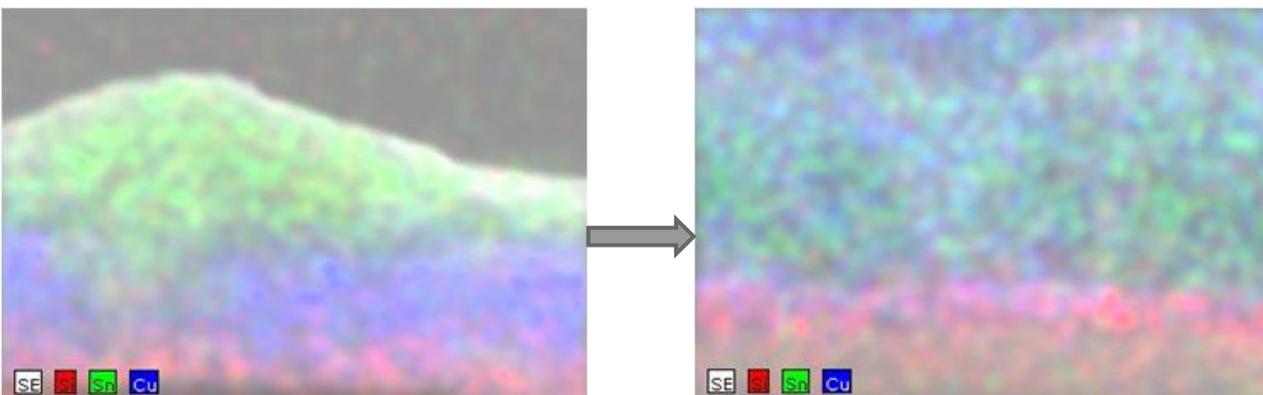
Origin of discrepancies:

- Error in mass measurement
- Sn(II) ion oxidation
- Sn(II) ion transport and depletion
- Competing reactions

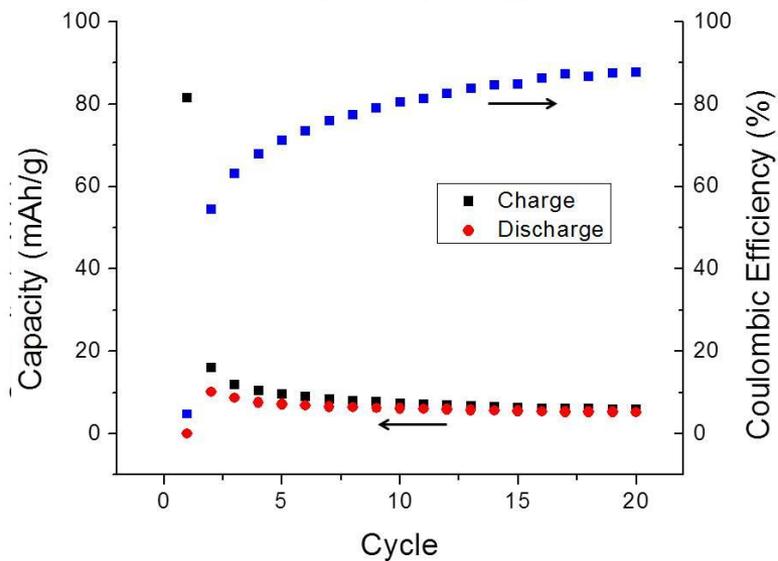
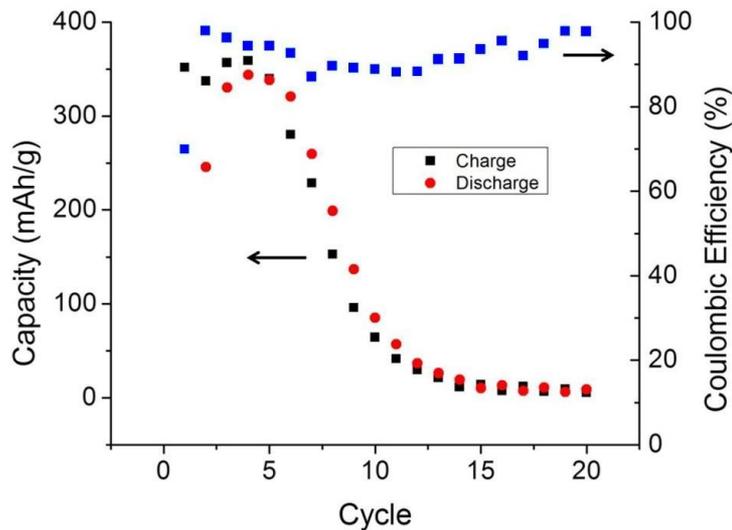
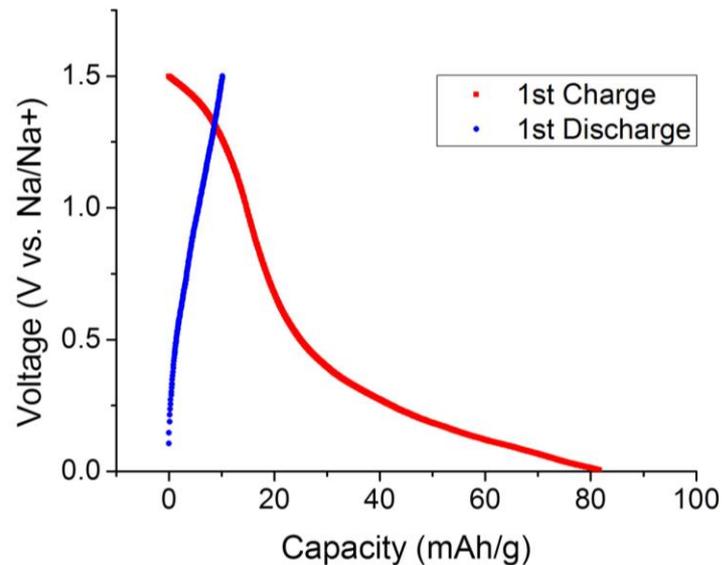
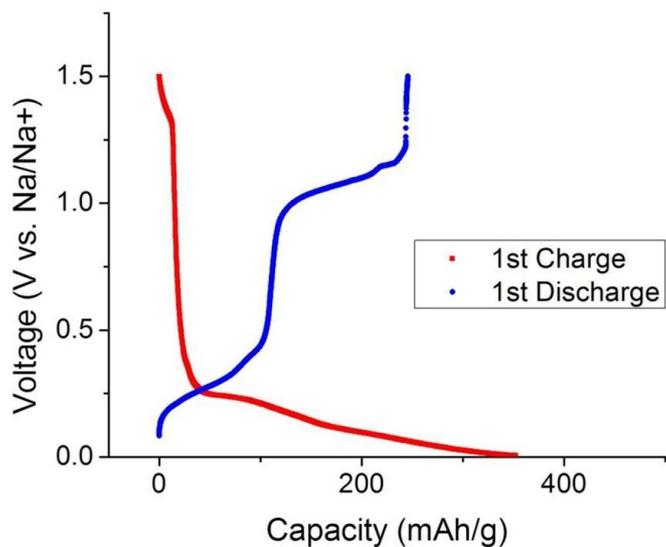
XRD and SEM/EDS

Sample	Annealing time (hrs)	Sn	Cu	Cu ₃ Sn	Cu ₆ Sn ₅
1A	20	X	X	X	
3	20	X	X	X	X
5	20	X	X	X	X
6	20	X	X	X	X
1a	120	X	X	X	
3a	120	X	X	X	X
5a	120	X	X	X	
6a	120	X	X	X	X
6b	120	X			
7	12		X	X	
Si3 (Control)	0	X	X		
Si5	2.116		X	X	
Si6	2.116		X	X	

- Initial deposition:
 - Based fabrication on stoichiometry, found that sufficient annealing would take long period of time
- IMC interface movement:
 - Predicted total consumption of Sn thin layer
 - XRD identification of only Cu₃Sn likely due to excess Cu



Battery Cell Testing



Conclusions

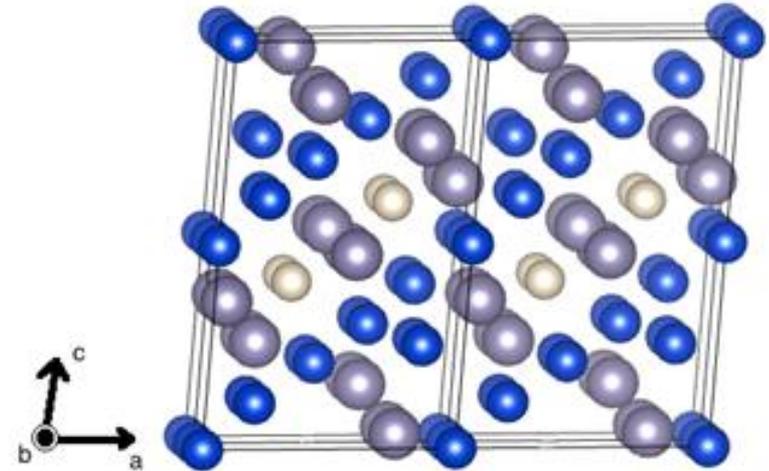
- First principles calculations indicate that Na can insert into $\eta\text{-Cu}_6\text{Sn}_5$ with a capacity of at least 82 Ah/kg and 62.6% volume expansion.

$$\text{Capacity} \left[\frac{\text{Ah}}{\text{kg}} \right] = \left(\frac{ze^-}{yA_m^{\text{alloy}}} \right) * F * \left(\frac{3600\text{kg}}{1000\text{hr}} \right)$$

- Volume expansion for the 2 Na atom system is 10% less than for pure Sn anodes, indicating that $\eta\text{-Cu}_6\text{Sn}_5$ anodes may have improved lifetime due to reduced expansion.
- Further fabrication and electrochemical characterization required to experimentally confirm DFT results.

Future Work

- Utilize Nudged Elastic Band (NEB) method to determine energy barriers for Na insertion into η -Cu₆Sn₅.
- Perform similar first principles calculations for ϵ -Cu₃Sn to compare to experimental results.
- Optimize Cu/Sn ratio for substrate to obtain η -Cu₆Sn₅.
- Explore other deposition methods (sputtering, PLD).
- Assemble and test half-cells with the η -Cu₆Sn₅ anode.



Acknowledgements

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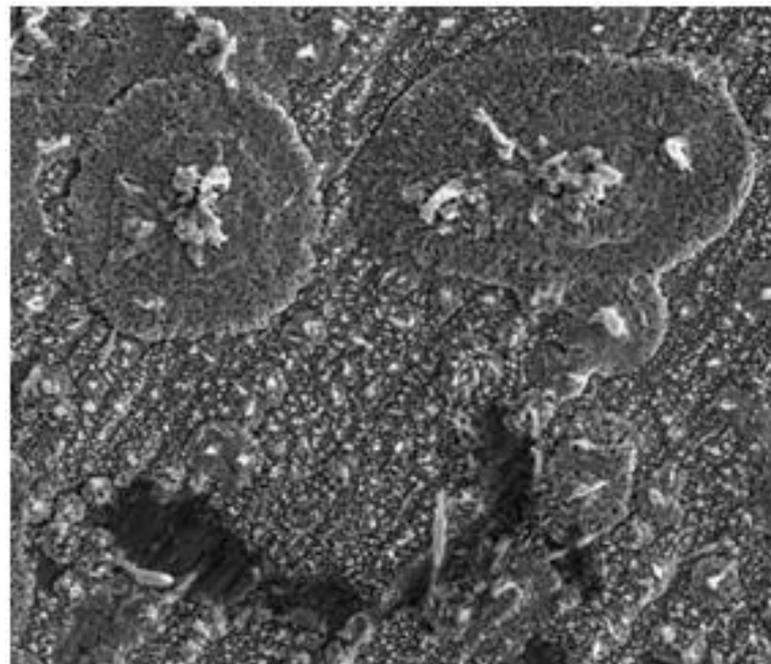
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Dr. Veith



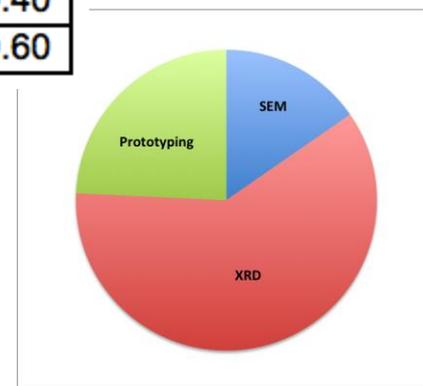
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Thank You

Budget and Resources

Purpose	Item	Cost/unit (\$/unit)	Units	Cost (\$)
Characterization	SEM in the Fablab	\$ 22.00	5	\$ 110.00
	X-Ray Diffraction	\$ 64.00	4	\$ 256.00
	X-Ray Diffraction	\$ 55.00	5	\$ 275.00
	Electron Probe Microanalysis	\$ 25.00	1	\$ 25.00
Modeling	XSEDE Allocation for VASP	\$ -	1	\$ -
Prototyping	Alumina Boat (50 x 40 x 18 mm)	\$ 5.00	3	\$ 15.00
	Beaker (400 ml)	\$ 3.24	1	\$ 3.24
	Hydroquinone Electrolyte (100 g)	\$ 24.09	1	\$ 24.09
	3M Electroplating Tape 470	\$ 24.34	1	\$ 24.34
	Thermal Evaporation	\$ 61.00	2	\$ 122.00
	Stir Bar	\$ 5.78	1	\$ 5.78
	Stopper	\$ 18.95	1	\$ 18.95
Total				\$ 879.40
Remaining				\$ 620.60

Calculation	Service Units Used
Bulk Energy of Cu ₁₂ Sn ₁₀	118
Relaxations of Na Insertion	119
Relaxation of 2 Na Structure	1583
Relaxation of 6 Na Structure	6127
Total Used	7947
Remaining	92053



Timeline

